

AGENDA

P-2.5 COMMITTEE FOR TANTALUM & NIOBIUM CAPACITORS

WEDNESDAY, September 27, 2006

2:00 to 4:00 PM

RENO, NEVADA

1. **COMMITTEE ORGANIZATION AND PROCEDURES**
 - 1.1 Membership and attendance
 - 1.2 Review and approve agenda
 - 1.3 Approve minutes of last meeting , Ft.Lauderdale, Spring 2006
 - 1.4 Correspondence
2. **OLD BUSINESS**
 - 2.1 Reports
 - 2.1.1 Passive Component Steering Committee (S.1).....Mike Lauri
(Announcement of future meeting dates and locations)
 - 2.1.2 Government Specifications and Standards..... DSCC Representative
 - 2.2 Surface Mount Tantalum Capacitors
 - 2.1 Status: Standard (EIA-535BAAC), Low ESR (EIA-535BAAE)
Discussion of new case sizes, ratings, or products....All Members
 - 2.2.2.1 Lead-frame less/face down termination molded specification?
 - 2.3 Hazardous Material IPC-1752 Spec
 - 2.4.1 Lead free solder topics - Tin Whiskers.....
 - 2.5 Tantalum Polymer spec - Status
 - 2.6 Discussion of moisture sensitivity tests for SMD solid and polymer tantalum
 - 2.6.1 Review existing specifications: J-Std-020C, IPC-9503 (MSL passives), IPC-9504 (Assembly Process Simulation for Non-IC Devices)
 - 2.7 Review and update EIA list of "active working projects
 - 2.8 Review Niobium/NbO draft specification/ PN number 5075
 - 2.9 Update EIA IS 717 Qualification specification PN 5097
3. **NEW BUSINESS**
 - 3.1.1 Address AEC Q200 Rev C preconditioning concerns
 - 3.1.2 Update 809 Applications Guideline. Include polymer, 150C. Face down terminations and mini-chip technologies....
 - 3.1.3 Status of Component Bulletin for Tin Whiskers as it relates to Tantalum
 - 3.2 Inputs for "All-Chairs Meeting"
4. **ADJOURNMENT**

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